60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV_{DSS}	$R_{DS(ON)}$ Max	I_D Max T_C = +25°C
60V	8mΩ @ V_{GS} = 10V	70A
	12mΩ @ V_{GS} = 4.5V	50A

Features

- Rated to 175°C – ideal for high ambient temperature environments
- 100% Unclamped Inductive Switching – ensures more reliable and robust end application
- Low On-Resistance
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

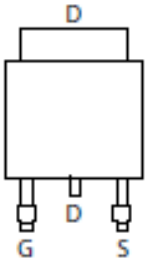
- Engine Management Systems
- Body Control Electronics
- DCDC Converters

Mechanical Data

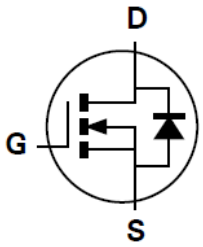
- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.33 grams (Approximate)

TO252

Top View



Pin Out Top View



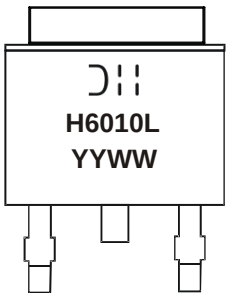
Equivalent Circuit

Ordering Information (Note 5)

Part Number	Case	Packaging
DMTH6010LK3Q-13	TO252	2,500/Tape & Reel

Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. For more information, please refer to http://www.diodes.com/product_compliance_definitions.html.
5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



= Manufacturer's Marking
H6010L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 15 = 2015)
WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	60	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current, V_{GS} = 10V (Note 6)	T_A = +25°C T_A = +70°C	I_D	14.8 11.9	A
Continuous Drain Current, V_{GS} = 10V (Note 7)	T_C = +25°C T_C = +100°C	I_D	70 50	A
Maximum Continuous Body Diode Forward Current (Note 7)		I_S	60	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I_{DM}	130	A
Avalanche Current, L = 0.1mH		I_{AS}	20	A
Avalanche Energy, L = 0.1mH		E_{AS}	20	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P_D	31	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	47	°C/W
Total Power Dissipation (Note 7)	P_D	60	W
Thermal Resistance, Junction to Case (Note 7)	$R_{\theta JC}$	2.5	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	-	-	V	V_{GS} = 0V, I_D = 1mA
Zero Gate Voltage Drain Current (Note 9)	I_{DSS}	-	-	1	µA	V_{DS} = 48V, V_{GS} = 0V
		-	-	100	µA	V_{DS} = 48V, V_{GS} = 0V, T_J = 125°C
Gate-Source Leakage	I_{GSS}	-	-	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	-	3	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	6.3	8	mΩ	V_{GS} = 10V, I_D = 20A
		-	8.3	12		V_{GS} = 4.5V, I_D = 20A
Diode Forward Voltage	V_{SD}	-	0.9	1.2	V	V_{GS} = 0V, I_S = 20A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	-	2090	-	pF	V_{DS} = 30V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	-	746	-		
Reverse Transfer Capacitance	C_{rss}	-	38.5	-		
Gate Resistance	R_g	0.1	0.59	1.8	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	-	19.3	-	nC	V_{DS} = 30V, I_D = 20A
Total Gate Charge (V_{GS} = 10V)	Q_g	-	41.3	-		
Gate-Source Charge	Q_{gs}	-	6	-		
Gate-Drain Charge	Q_{gd}	-	8.8	-		
Turn-On Delay Time	$t_{D(ON)}$	-	5.7	-	ns	V_{DD} = 30V, V_{GS} = 10V, I_D = 20A, R_g = 3Ω
Turn-On Rise Time	t_R	-	4.3	-		
Turn-Off Delay Time	$t_{D(OFF)}$	-	23.4	-		
Turn-Off Fall Time	t_F	-	9.7	-		
Body Diode Reverse Recovery Time	t_{RR}	-	35.4	-	ns	I_F = 20A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	-	38.2	-	nC	

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.

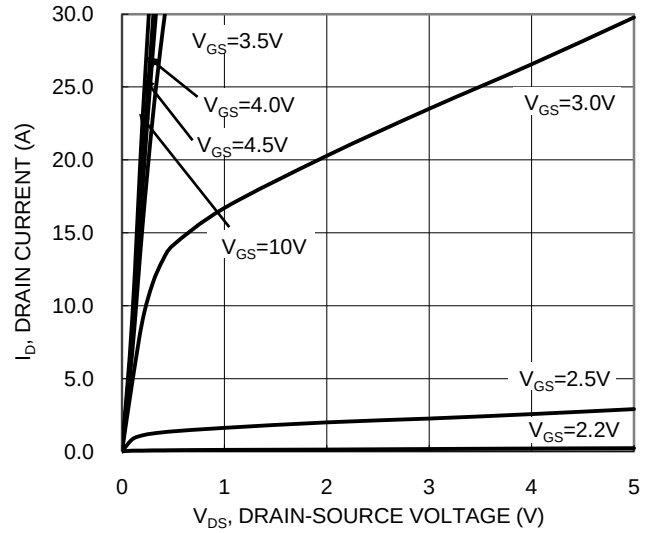


Figure 1. Typical Output Characteristic

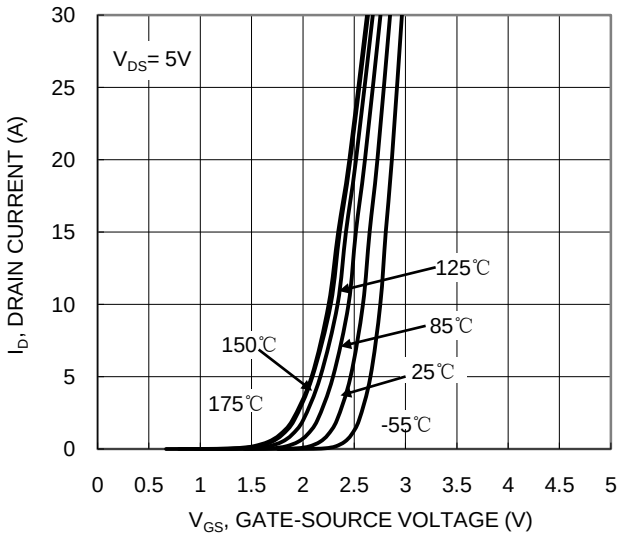


Figure 2. Typical Transfer Characteristic

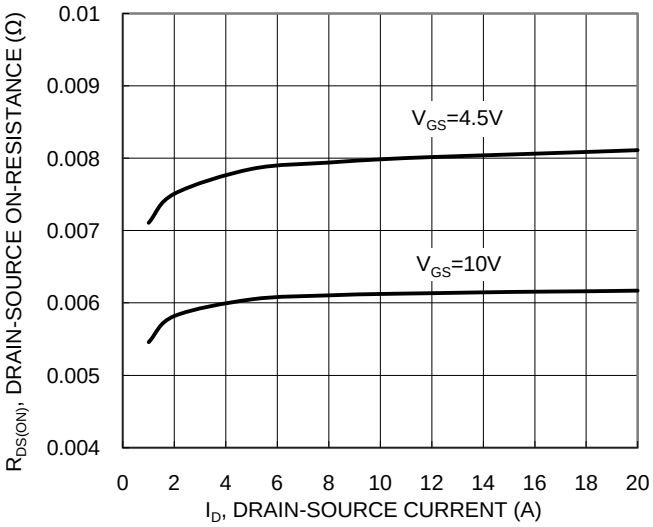


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

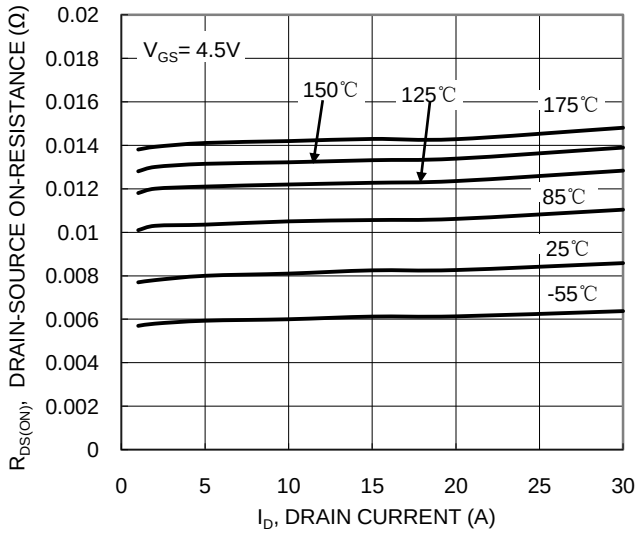


Figure 4. Typical On-Resistance vs. Drain Current and Temperature

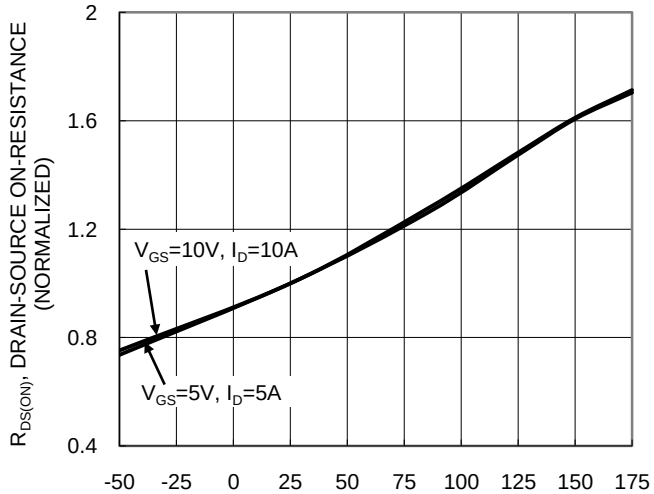


Figure 5. On-Resistance Variation with Temperature

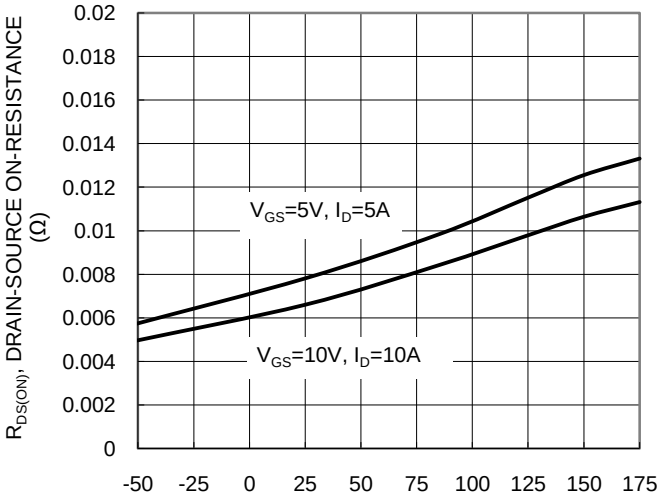


Figure 6. On-Resistance Variation with Temperature

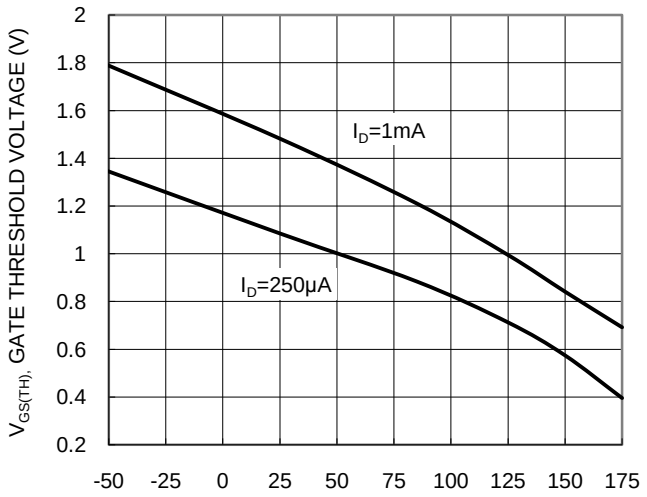


Figure 7. Gate Threshold Variation vs. junction Temperature

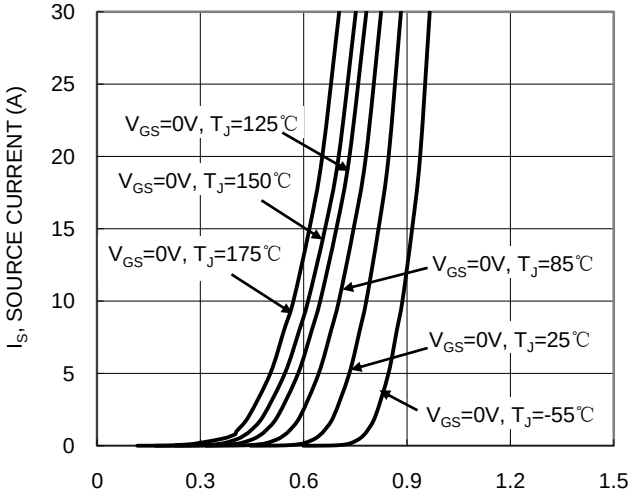


Figure 8. Diode Forward Voltage vs. Current

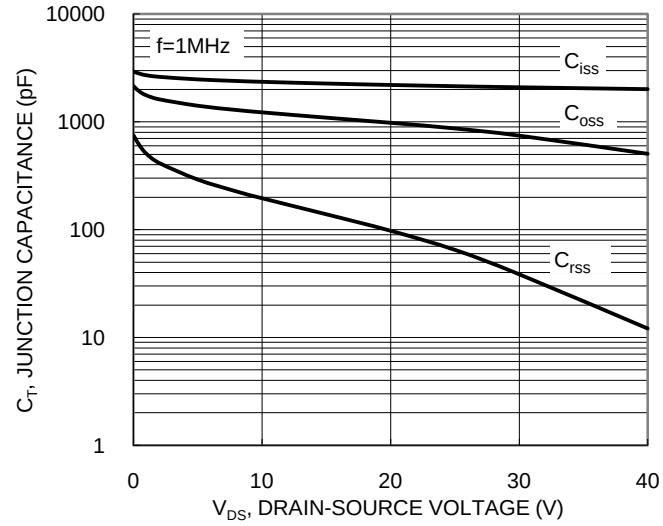


Figure 9. Typical Junction Capacitance

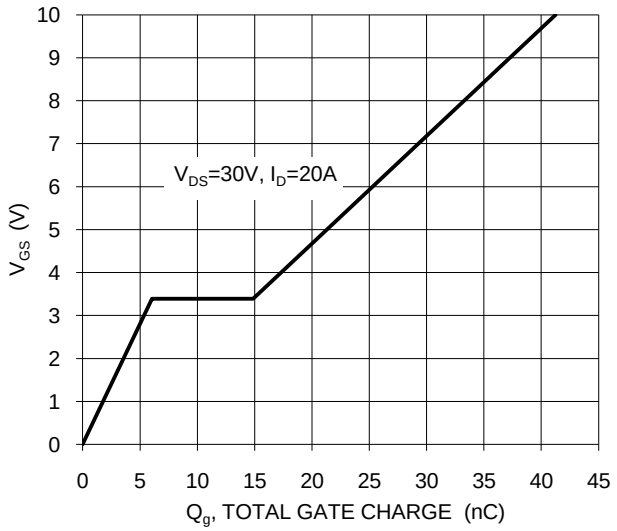


Figure 10. Gate Charge

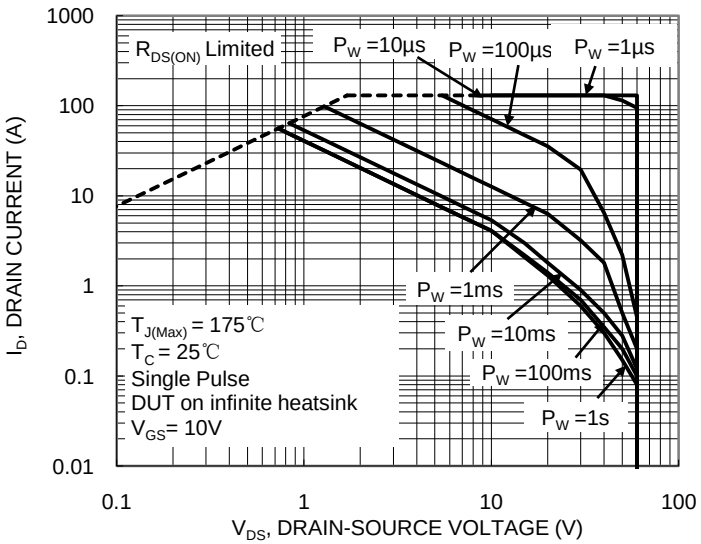


Figure 11. SOA, Safe Operation Area

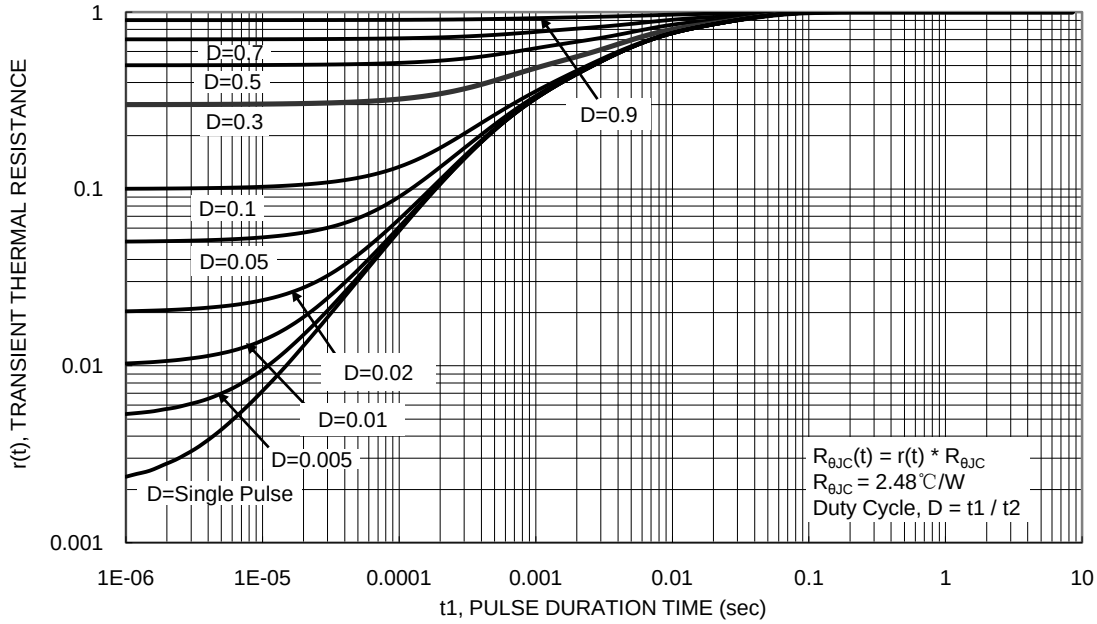
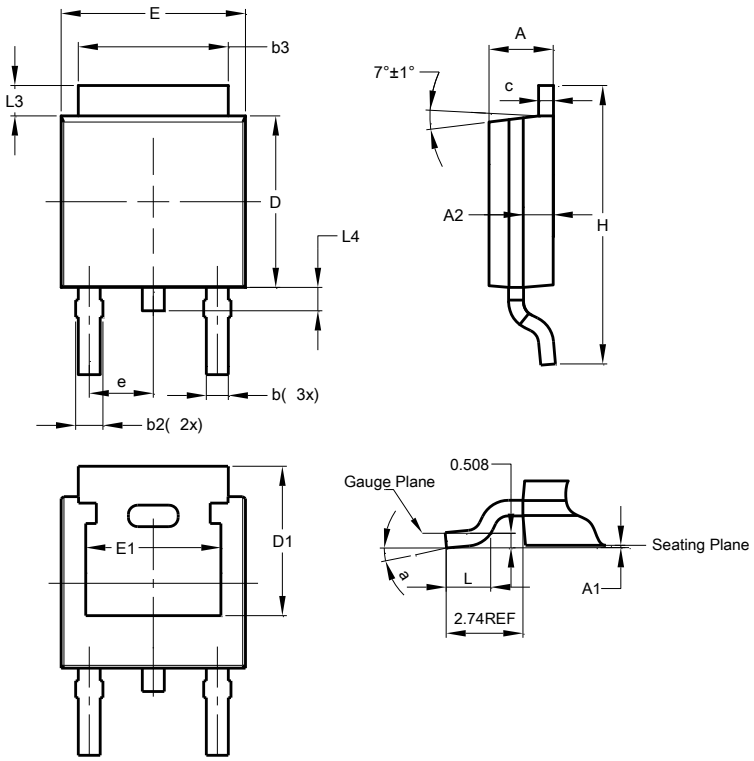


Figure 12 .Transient Thermal Resistance

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

TO252 (DPAK)

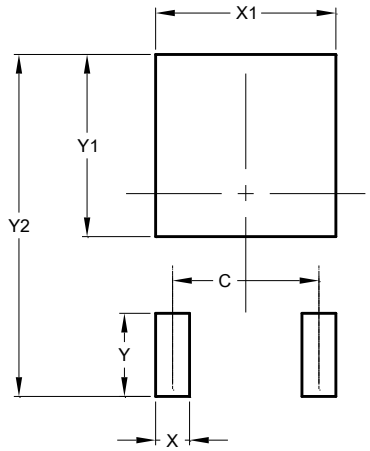


TO252 (DPAK)			
Dim	**Min**	**Max**	**Typ**
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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